

118-09C**SOLVENT-RESISTANT ELECTRICALLY CONDUCTIVE INK**

DESCRIPTION: 118-09C is a single component, solvent-resistant, electrically conductive ink, coating and adhesive suitable for screen-printing circuit lines. This product features excellent adhesion to Kapton, Mylar, glass, polycarbonate and a variety of other substrates. Unlike conventional conductive materials, this product is very resistant to methyl ethyl ketone. It is also very resistant to scratching and creasing. Some applications for 118-09C include, but are not limited to, emi/rfi shielding of polyimide flexible circuits, polymer thick film circuitry, membrane switches, electrical attachments for surface mounted devices, bus bars on Indium Tin Oxide sputtered surfaces, and anode coatings for tantalum capacitors. This product is designed for use in crossovers with CMI product 116-20, a UV curable dielectric. 118-09C is the pre-catalyzed version of 118-09A/B

MIXING INSTRUCTIONS: 118-09C comes premixed with the appropriate amount of curing agent. It is important to resuspend any settled filler before using. Product may be thinner by adding small amounts of CMI 113-12 thinner.

TYPICAL CURED PROPERTIES:

Viscosity (cps.)	15,000 – 20,000
Filler	Silver
Percent Silver (cured)	> 85
Crease Resistance	Excellent
Volume Resistance (ohm-cm)	0.00005
Sheet Resistivity (ohm/sq./mil)	0.019
Solderable	No
Hydrolytic Stability	Excellent
Useful Temperature Range (°C)	-55 to +200
Thermal Stability (°C)	Good to +280

CURE SCHEDULE:

80°C	4 hrs.
100°C	1 hr.
125°C	30 min.
150°C	15 min.
175°C	10 min.

STORAGE: Shelf life: ≤ 2 weeks at 25°C or 6 months at -40°C in unopened containers.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to suitability in particular application or possible infringements on patents.

REVISION DATE: 06/19/18 REVISION: B